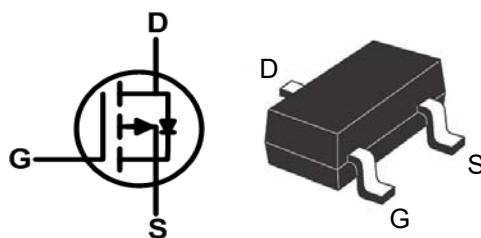


Marking: 3012

3012

P-Channel Enhancement Mode Power MOSFET
● Features

$V_{DS} = -12V$
 $I_D = -5A$
 $R_{DS(ON)} \leq 0.032\Omega (V_{GS} = -4.5V)$

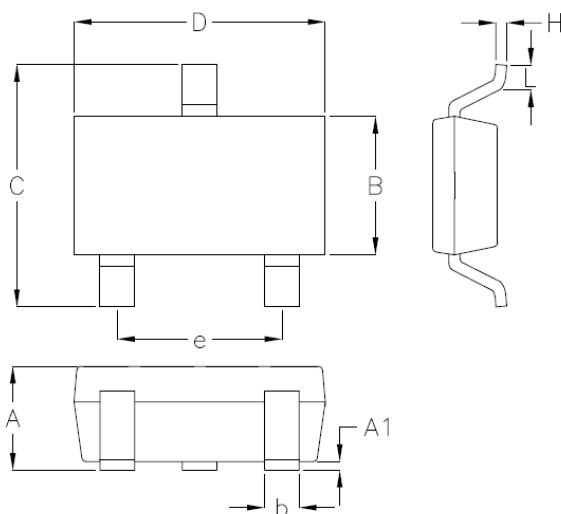
● Pin Configurations

● General Description

The TPM3012V1SX is the high cell density trench P-ch MOSFETs, which provides excellent $R_{DS(ON)}$ and efficiency for most of the small power switching and load switch applications.

The TPM3012V1SX meet the RoHS and Green Product requirement with full function reliability approved.

● Package Information

SOT23-3L



SYMBOLS	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	0.890	1.295	0.035	0.051
A1	0.000	0.152	0.000	0.006
B	1.397	1.803	0.055	0.071
b	0.356	0.508	0.014	0.020
C	2.591	3.010	0.102	0.119
D	2.692	3.099	0.106	0.122
e	1.793	2.007	0.070	0.079
H	0.080	0.254	0.003	0.010
L	0.300	0.610	0.012	0.024

P-Channel Enhancement Mode Power MOSFET

● **Absolute Maximum Ratings (@ $T_A=25^\circ C$ unless otherwise noted)**

Parameter		Symbol	Ratings	Unit
Drain-Source Voltage		V_{DSS}	-12	V
Gate Source Voltage		V_{GSS}	± 12	V
Drain Current (Continuous) *A	$T_A=25^\circ C$	I_D	-5	A
	$T_A=70^\circ C$		-3.9	
Drain Current (Pulse) *B		I_{DM}	-16	A
Power Dissipation *C	$T_A=25^\circ C$	P_D	1.5	W
Operating Temperature/ Storage Temperature		T_J/T_{STG}	-55 to 150	°C

● **Thermal Characteristics**

Parameter	Symbol	Ratings	Unit
Thermal Resistance ,Junction-to-Ambient *A	$R_{\theta JA}$	125	°C/W
Thermal Resistance Junction-Case *A	$R_{\theta JC}$	82	°C/W

● **Electrical Characteristics (@ $T_A=25^\circ C$ unless otherwise noted)**

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS}=0V, I_D=-250\mu A$		-12	-18	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=-12V, V_{GS}=0V$	--	--	1	uA
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{DS}=V_{GS}, I_{DS}=-250\mu A$	-0.4	--	-1	V
Gate Leakage Current	I_{GSS}	$V_{GS}=\pm 12V, V_{DS}=0V$	--	--	± 100	nA
Drain-Source On-state Resistance *B	$R_{DS(on)}$	$V_{GS}=-4.5V, I_D=-1A$	--	23	32	mΩ
		$V_{GS}=-2.5V, I_D=-0.5A$	--	35	50	mΩ
Forward Transconductance	g_{fs}	$I_D=-2A, V_{DS}=-5V$	--	6	--	S
Gate Resistance	R_g	$V_{GS}=0V, V_{DS}=0V, f=1MHz$	--	16	32	Ω
Total Gate Charge	Q_g	$V_{GS}=-4.5V, V_{DD}=-10V, I_D=-4A$	--	8	--	nC
Gate- Source Charge	Q_{gs}		--	1.14	--	nC
Gate- Drain Charge	Q_{gd}		--	1.5	--	nC
Turn-on Delay Time	$t_{d(on)}$	$V_{GS}=-4.5V, V_{DD}=-10V, R_L=2.5\Omega, R_{GEN}=3\Omega$	--	13.6	--	ns
Turn-on Rise Time	t_r		--	35	--	ns
Turn-off Delay Time	$t_{d(off)}$		--	32	--	ns
Turn-off Fall Time	t_f		--	10	--	ns
Input Capacitance	C_{iss}	$V_{GS}=0V, V_{DS}=-10V, f=1MHz$	--	984	--	pF
Output Capacitance	C_{oss}		--	219	--	pF
Reverse Transfer Capacitance	C_{rss}		--	116	--	pF

P-Channel Enhancement Mode Power MOSFET

- Reverse Diode Characteristics (@ $T_A=25^\circ C$ unless otherwise noted)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Continuous Source Current *A,D	I_S	$V_G=V_D=0V$, Force Current	--	--	-4.6	A
Pulsed Source Current *B,D	I_{SM}		--	--	-16	A
Diode Forward Voltage *B	V_{SD}	$I_{SD}=-1A$, $V_{GS}=0V$	--	--	-1.2	V

A: The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.

B: The data tested by pulsed , pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$.

C: The power dissipation is limited by 150°C junction temperature.

D: The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

P-Channel Enhancement Mode Power MOSFET

- TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

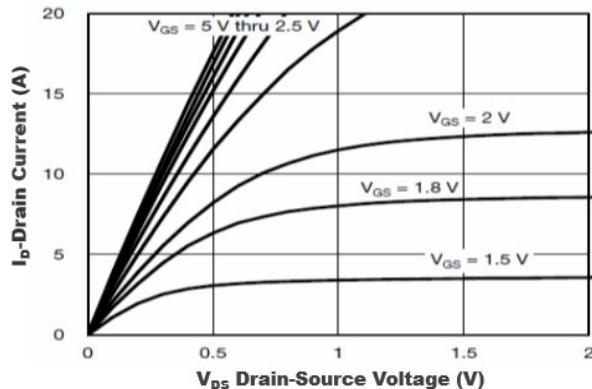


Figure1. Output Characteristics

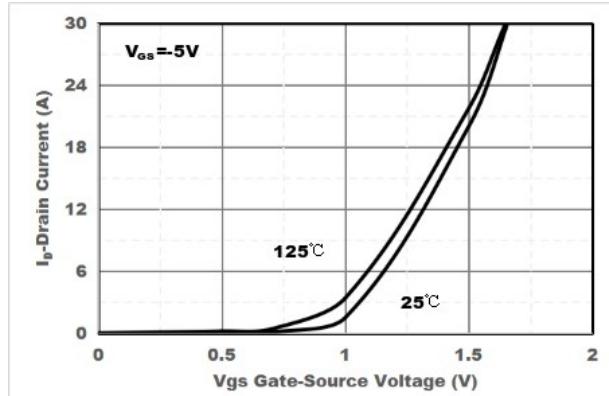


Figure2. Transfer Characteristics

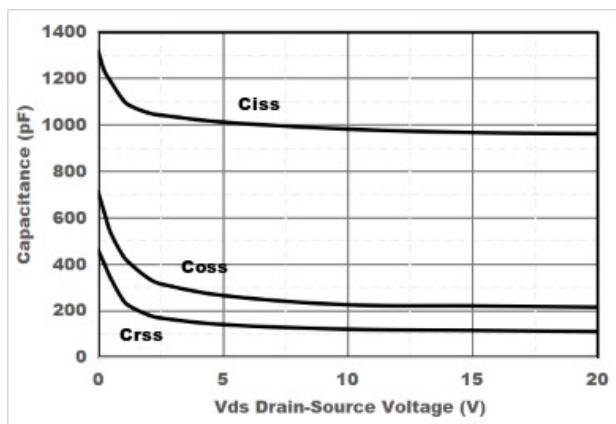


Figure3. Capacitance Characteristics

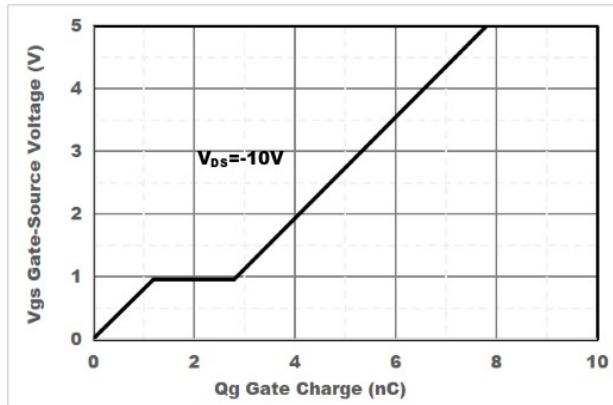


Figure4. Gate Charge

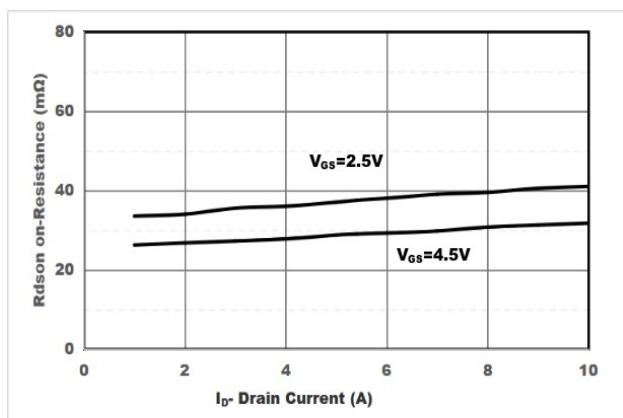


Figure5. Drain-Source on Resistance

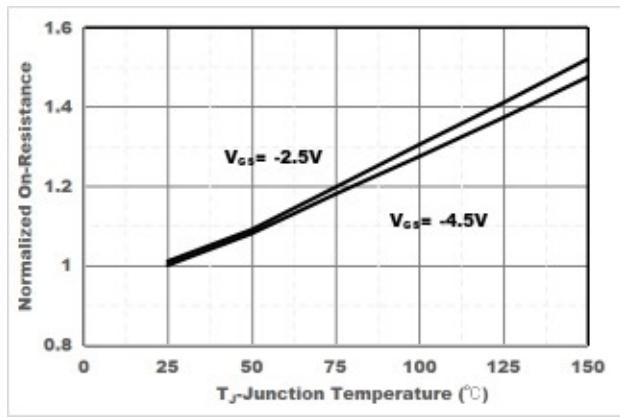


Figure6. Drain-Source on Resistance

P-Channel Enhancement Mode Power MOSFET

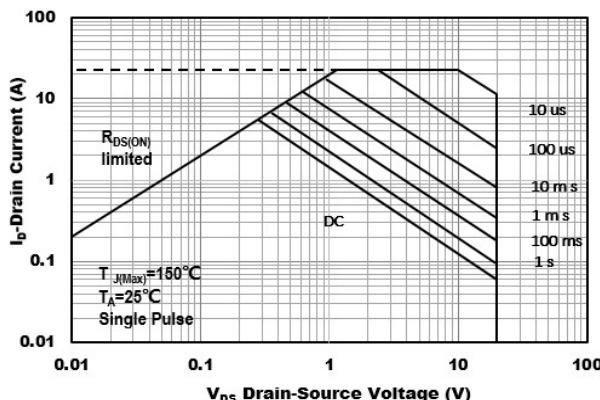


Figure7. Safe Operation Area

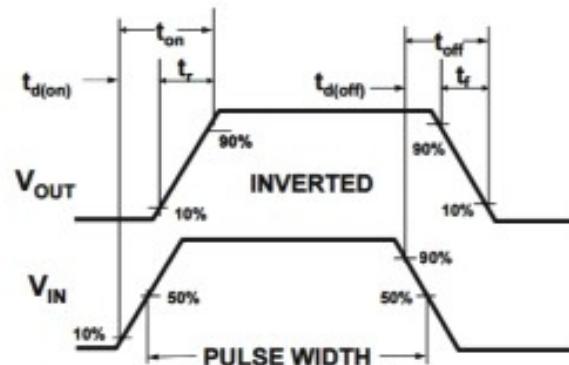
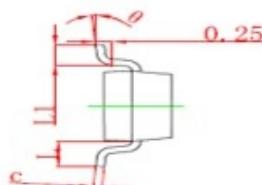
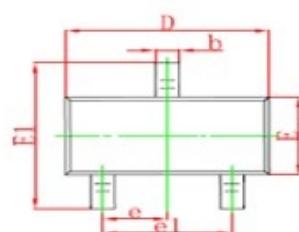


Figure8. Switching wave

SOT-23 Package information



Symbol	Dimensions in Millimeter		Dimensions in Inches	
	Min	Max	Min	Max
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950Type		0.037Type	
e1	1.800	2.000	0.071	0.079
L	0.550REF		0.220REF	
L1	0.300	0.500	0.012	0.020
θ	0 °	8 °	0 °	8 °

SOT-23 Suggested Pad Layout

